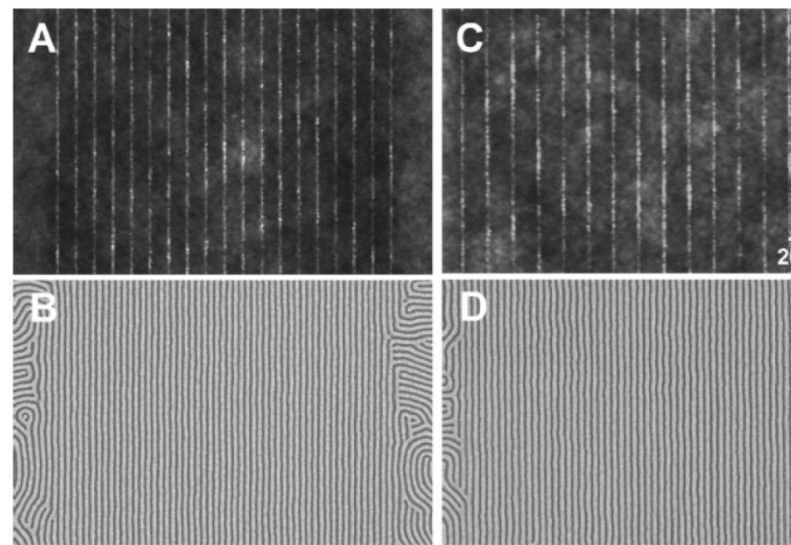
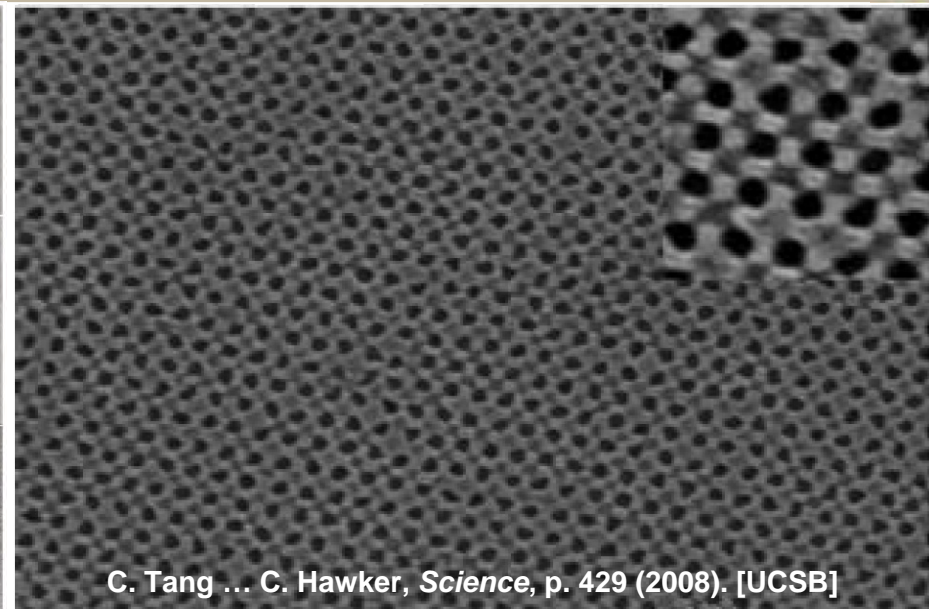
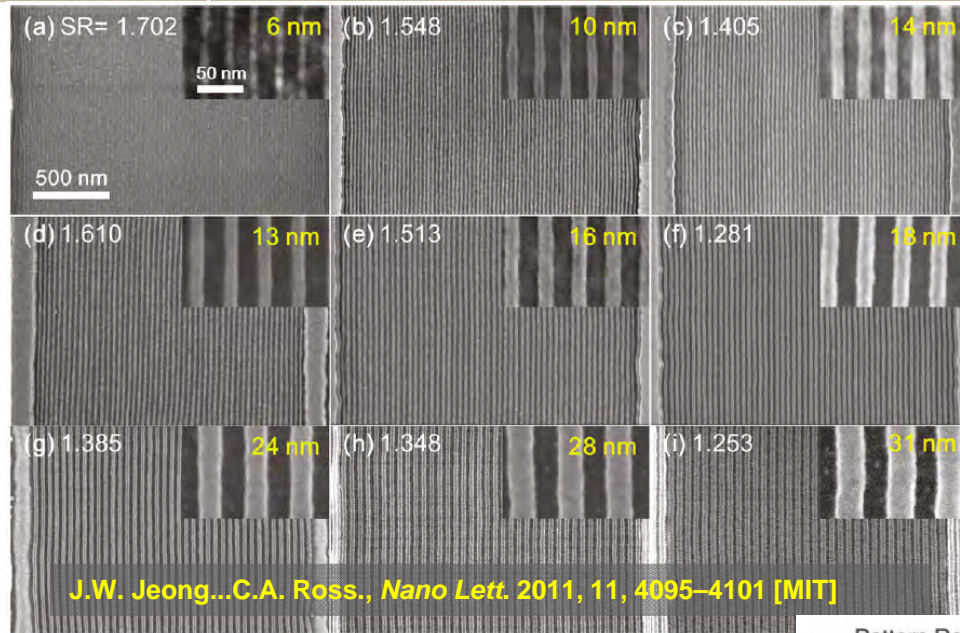


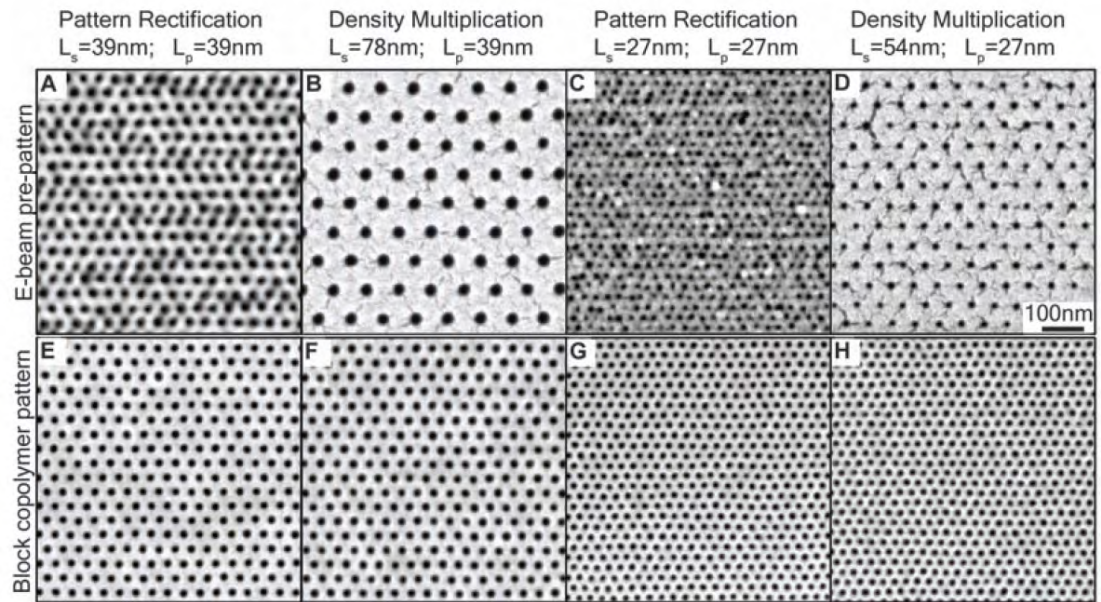


# Directed Self-Assembly for the Semiconductor Industry

H.-S. Philip Wong, Chris Bencher#  
Linda He Yi, Xin-Yu Bao, Li-Wen Chang  
*Stanford University, #Applied Materials*



J. Y. Cheng et al., *Adv. Mater.* 2008, 20, 3155–3158 [IBM]



R. Ruiz...P. Nealey, *Science* **321**, 936 (2008) [Hitachi, Wisconsin]





# Device Fabrication

Does not require  
long range order

Nangate cell library: <http://www.nangate.com>

J. Stork, TI (2007), Stanford seminar



# Device Fabrication Requires

- Multiple-pitch
- Multiple-ordering
- Multiple-size
- One layer process
- Single material system
- Industrial compatible process
- **Transparent to circuit designers**

Technical  
requirement

Practicality  
(i.e. cost)

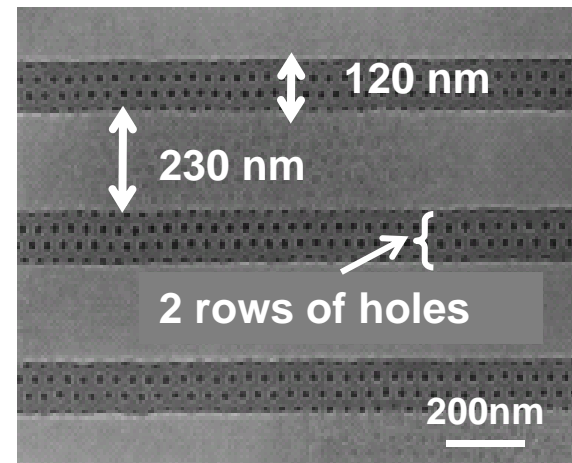
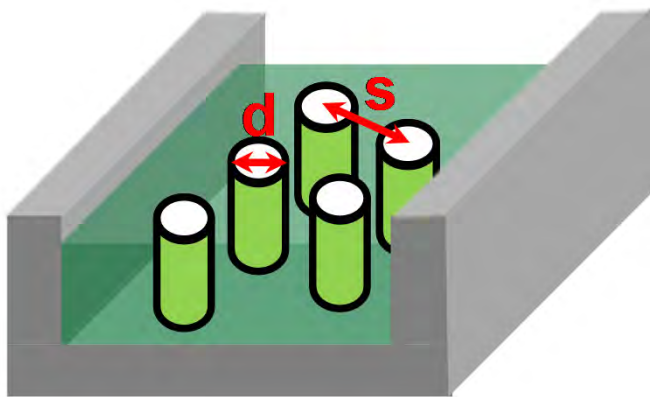
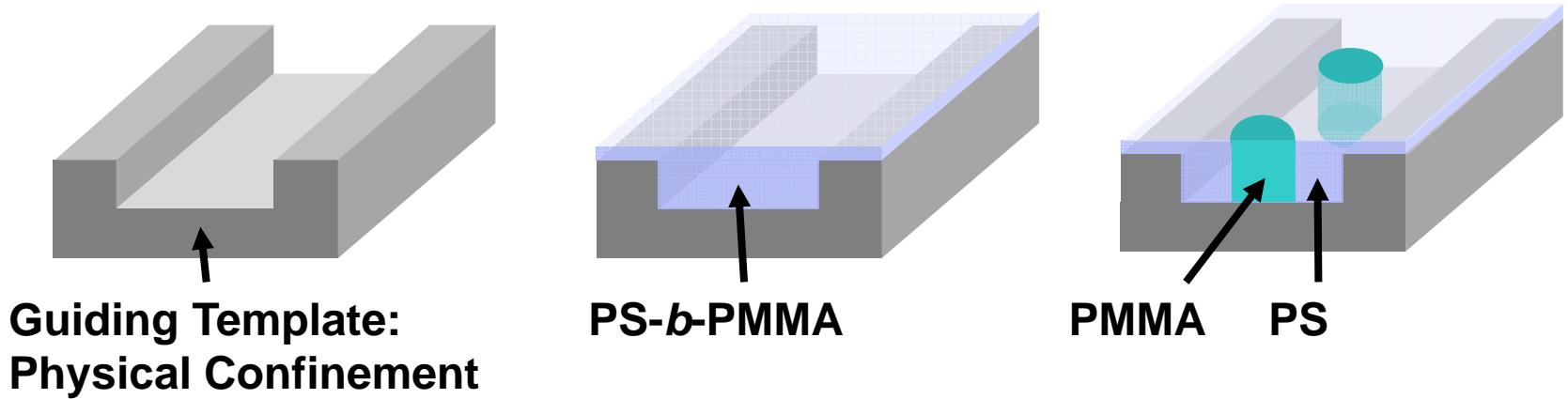


Why don't we place the shapes where we want them to be?



Adapted from: [ucsusa.org](http://ucsusa.org)

# Directed Self-Assembly by Physical Confinement

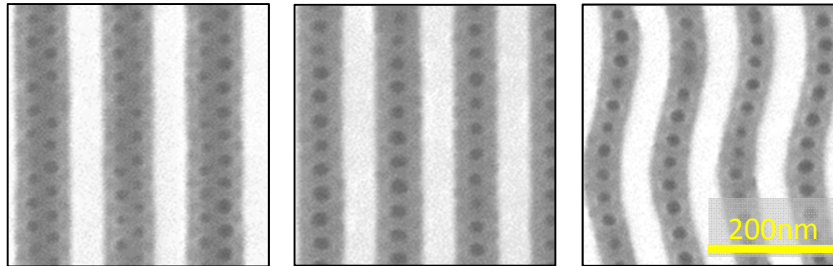


L.-W. Chang...H.-S. P. Wong, *IEDM*, p. 879, 2009

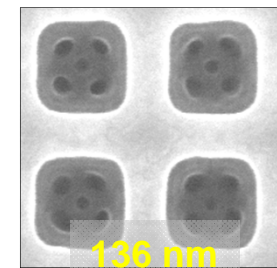
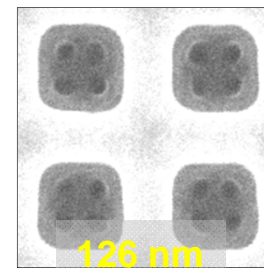
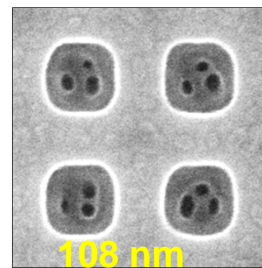
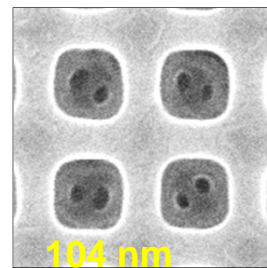
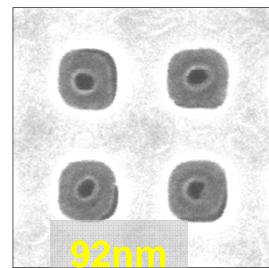
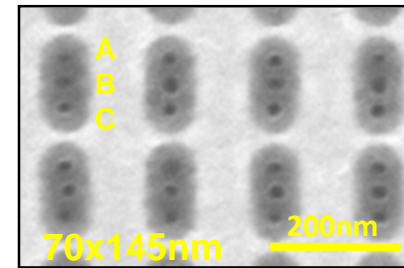
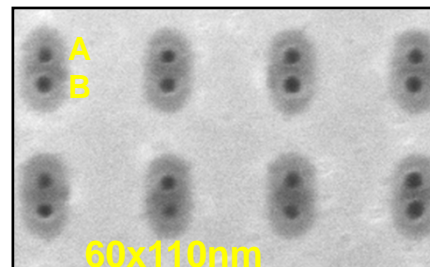
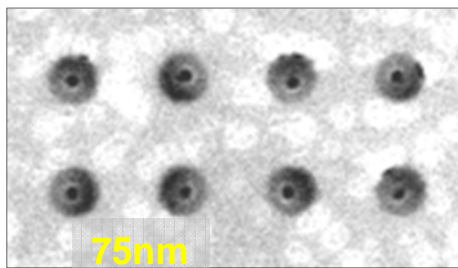


# Control of DSA with Small Guiding Templates

- **Size Comparable to self-assembly dimensions**



Flexible and precise control knobs:  
Thickness, size, density



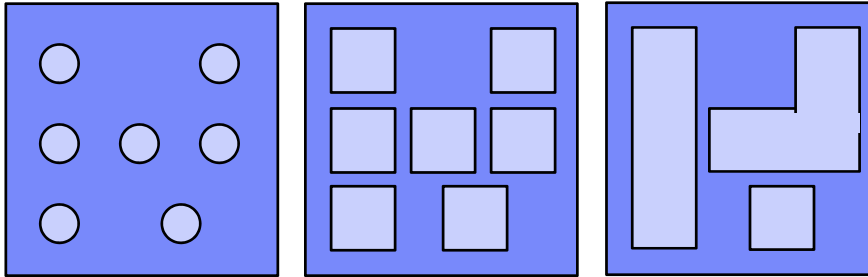
scale bar 200nm

Square lattice

Rhombic lattice



# Small Templates

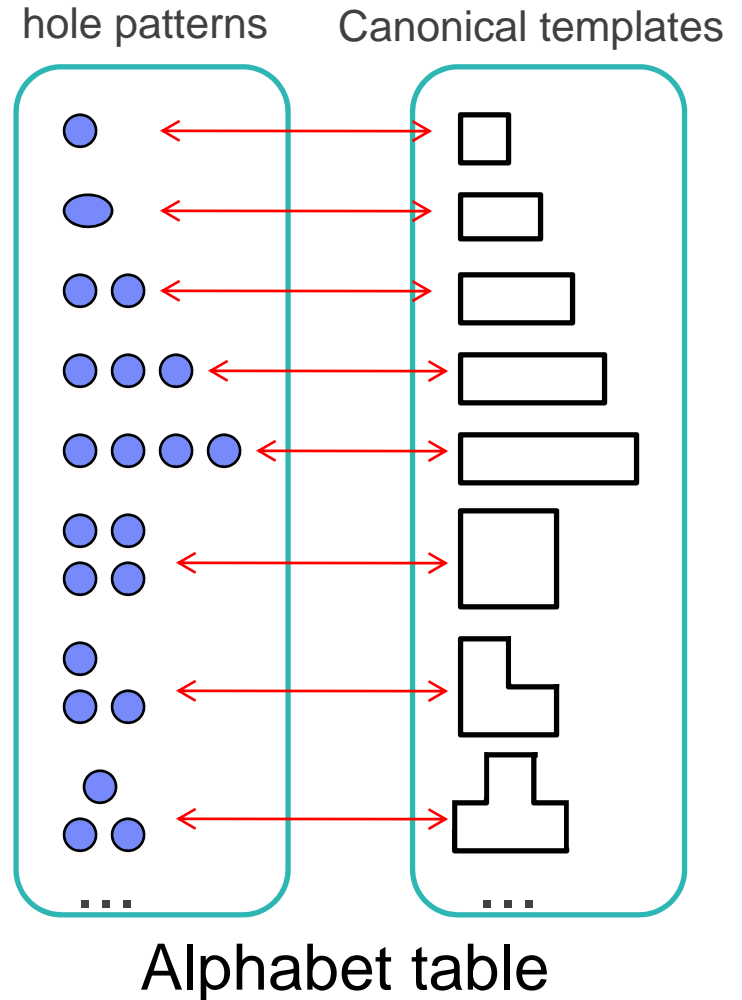


## Canonical templates:

- Simplest template set to form desired patterns
- Manufacturable with current litho tech.

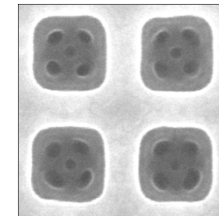
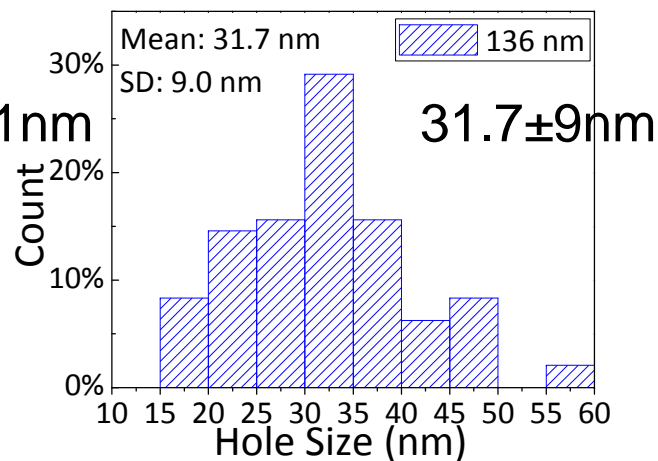
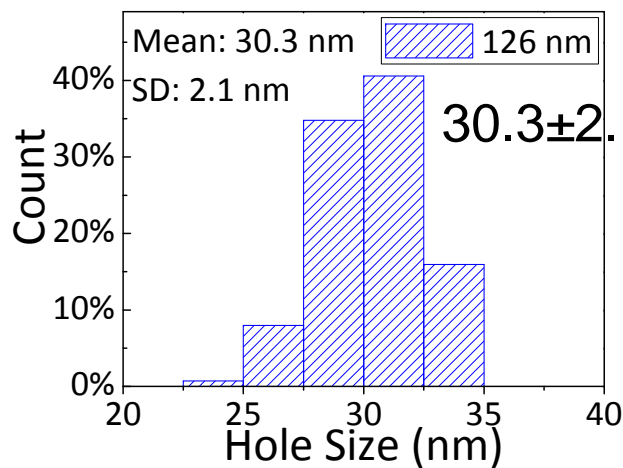
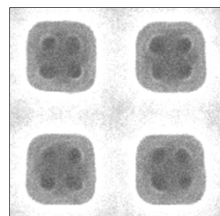
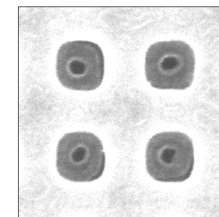
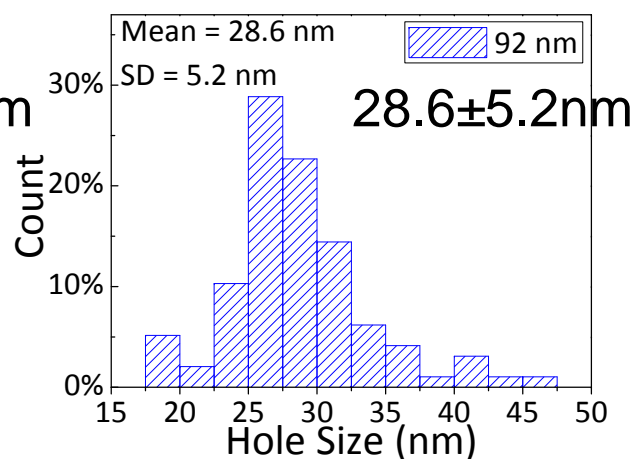
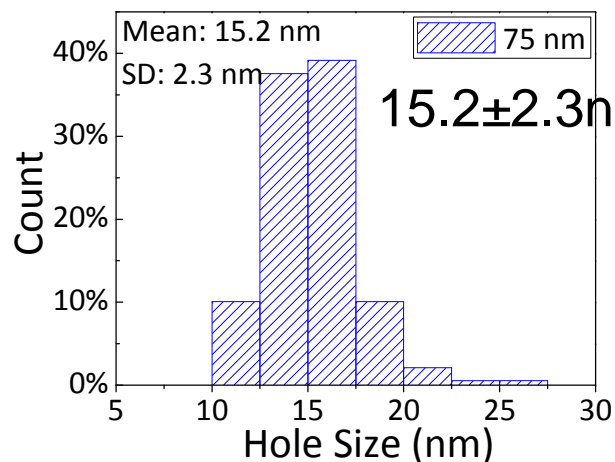
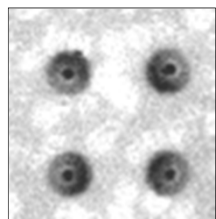
## Design Rules:

- The standards to disassemble a layout to canonical templates and reassemble canonical templates to pattern devices





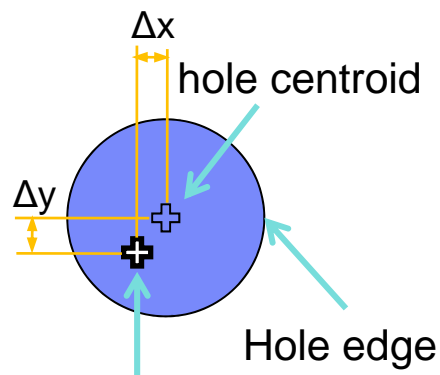
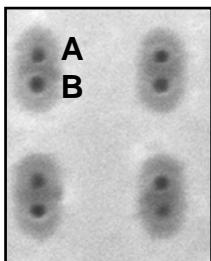
# Square Template DSA Pattern Size Analysis



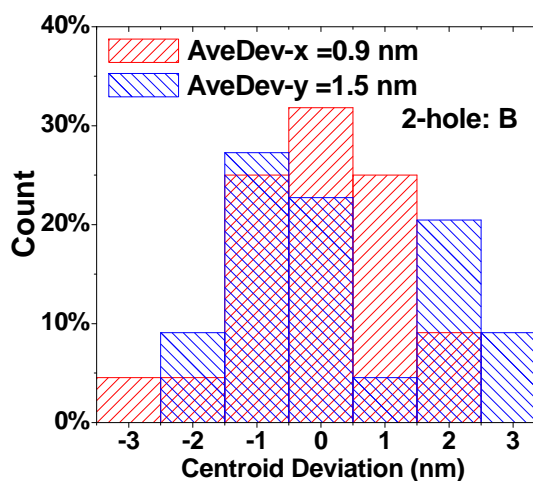
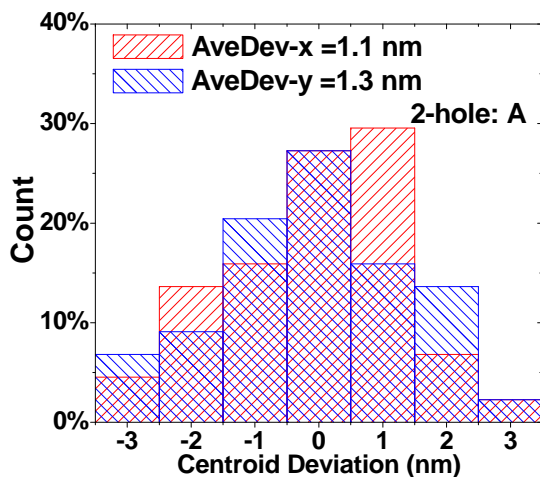
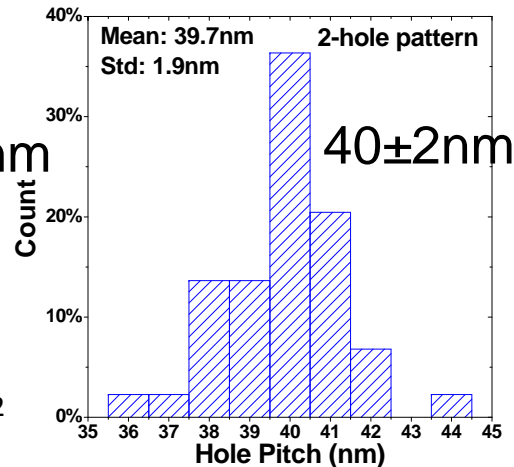
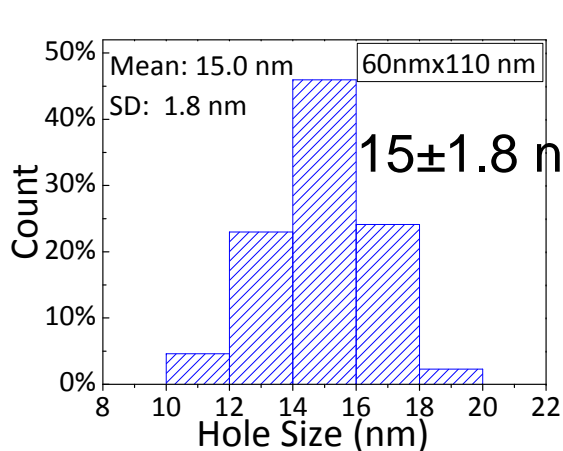
H. Yi ... H.-S. P. Wong, *Adv. Mater.*, 2012



# 2-Hole Pattern Analysis



Average centroid  
 Overlay accuracy:  
 Average absolute deviation



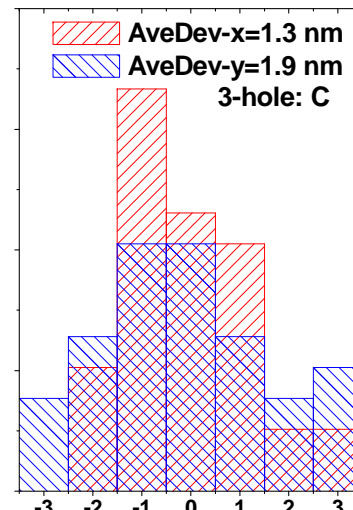
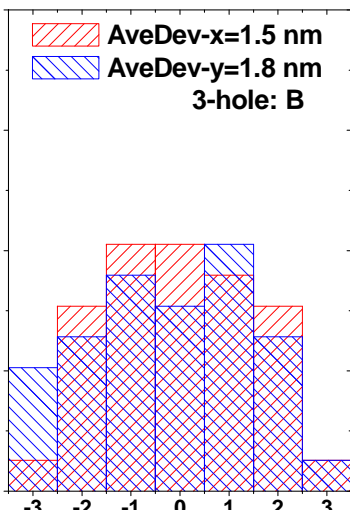
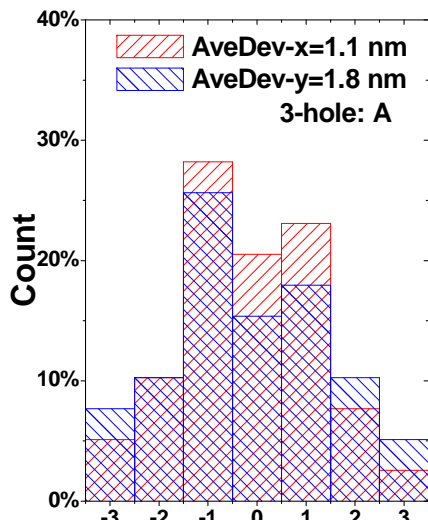
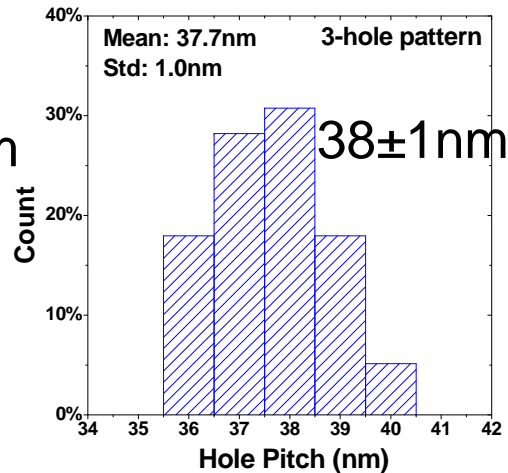
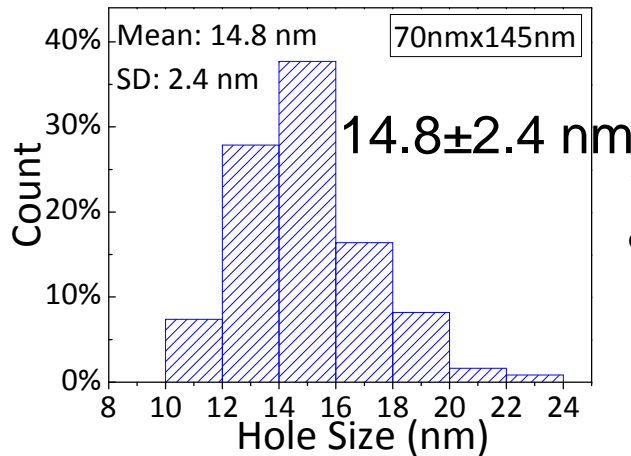
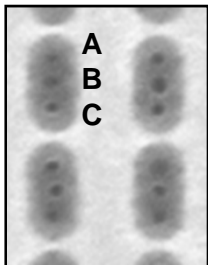
$\Delta x \sim 1\text{nm}$   
 $\Delta y \sim 1.5\text{nm}$

H. Yi ... H.-S. P. Wong, *Adv. Mater.*, 2012





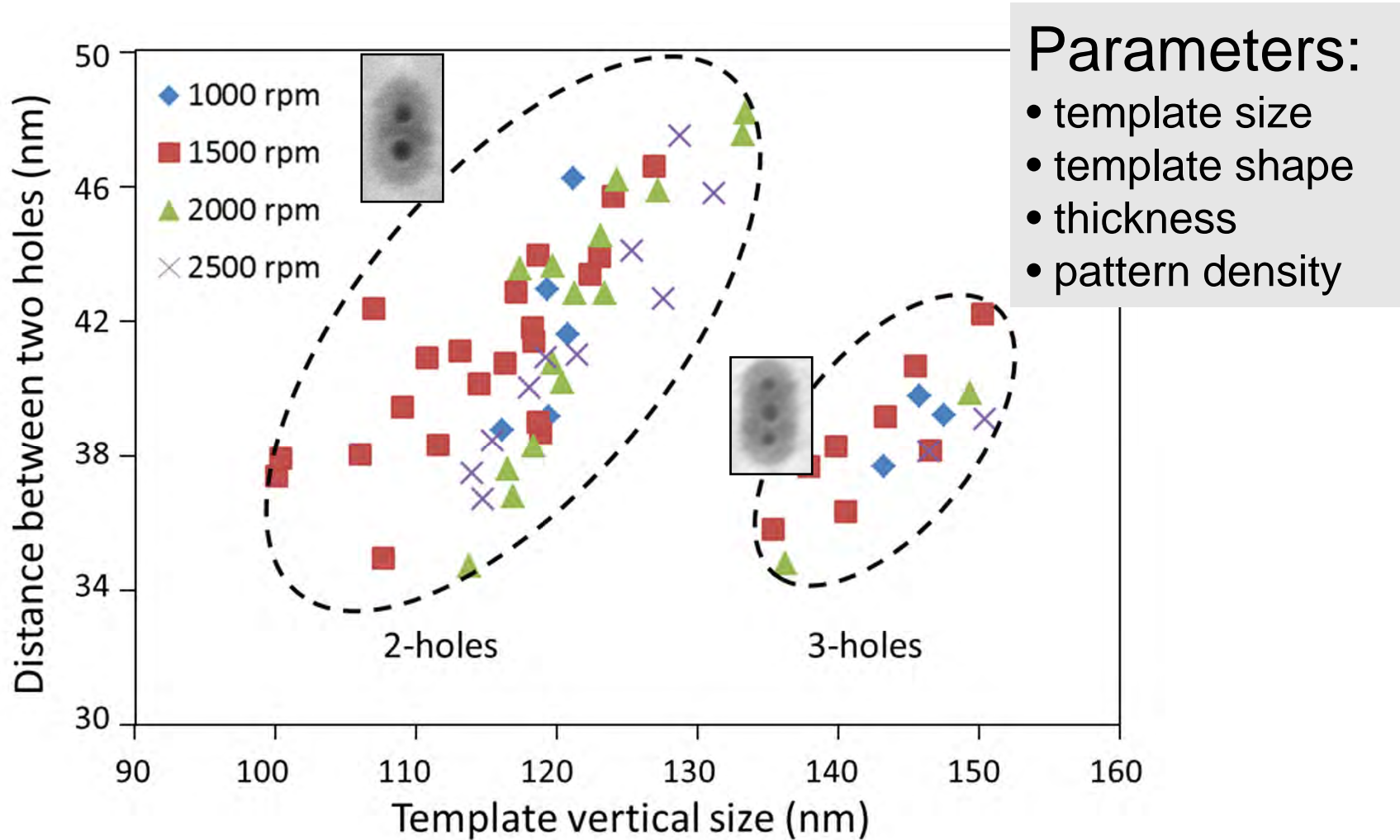
# 3-Hole Pattern Analysis



$\Delta x \sim 1.5 \text{ nm}$   
 $\Delta y \sim 1.9 \text{ nm}$

H. Yi ... H.-S. P. Wong, *Adv. Mater.*, 2012

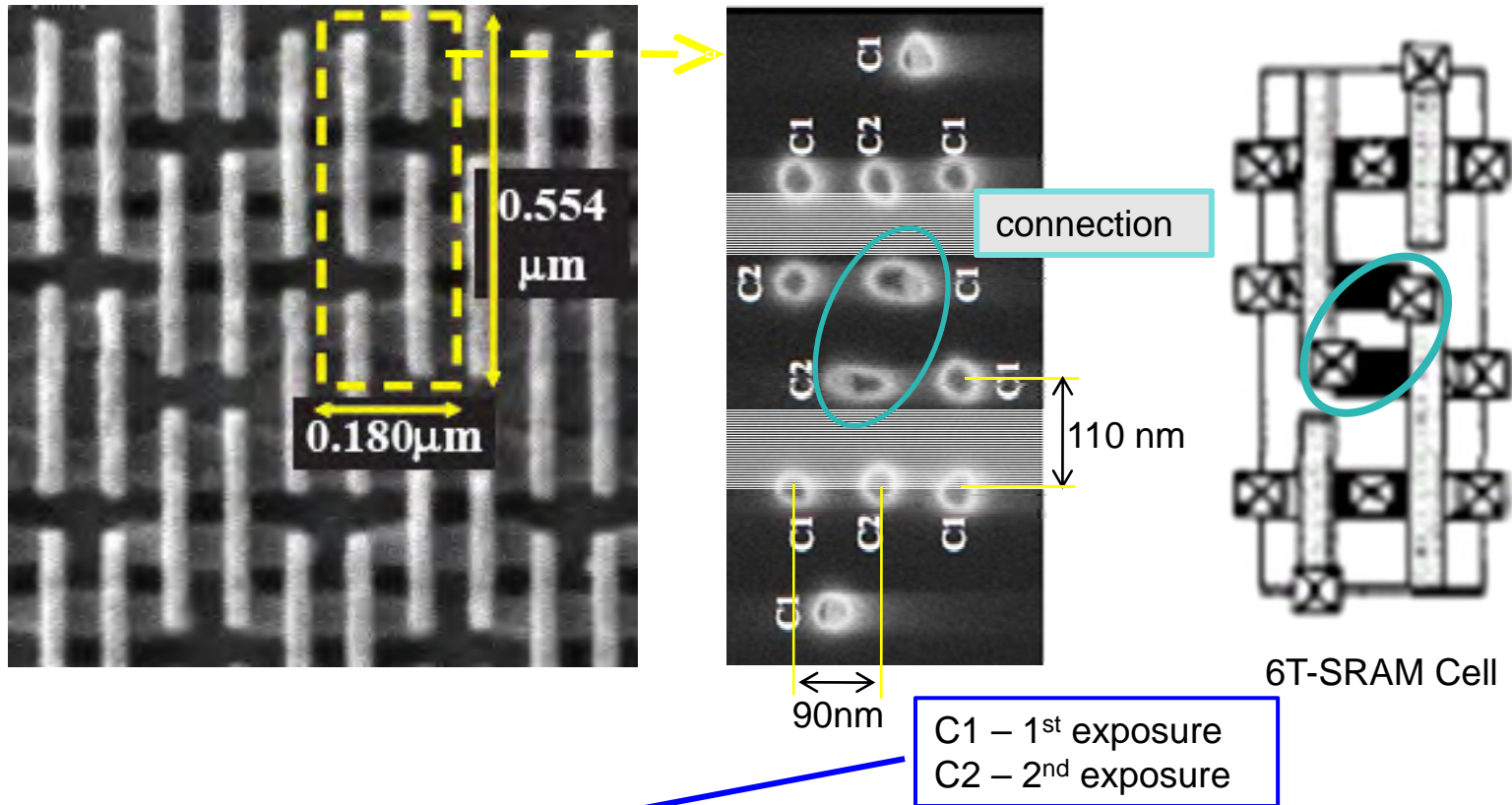
# Design Space for 2-3 Hole Guiding Templates



H. Yi ... H.-S. P. Wong, *Adv. Mater.*, 2012



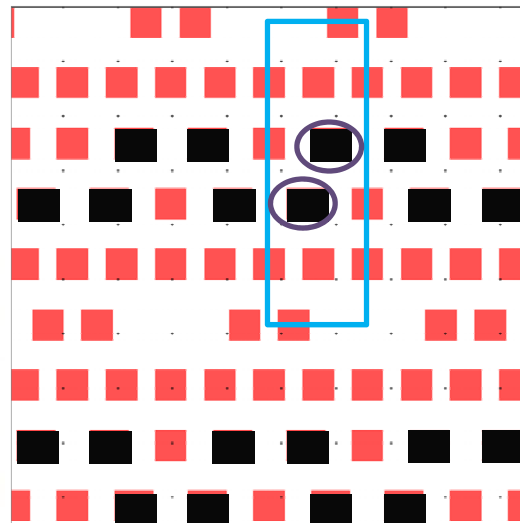
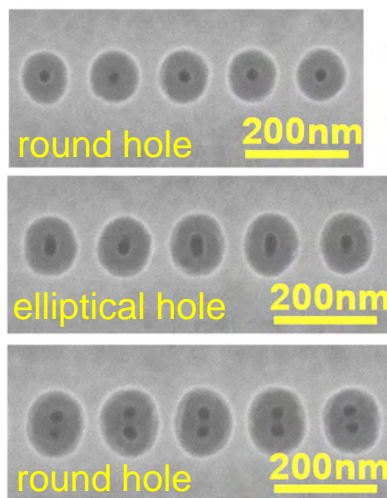
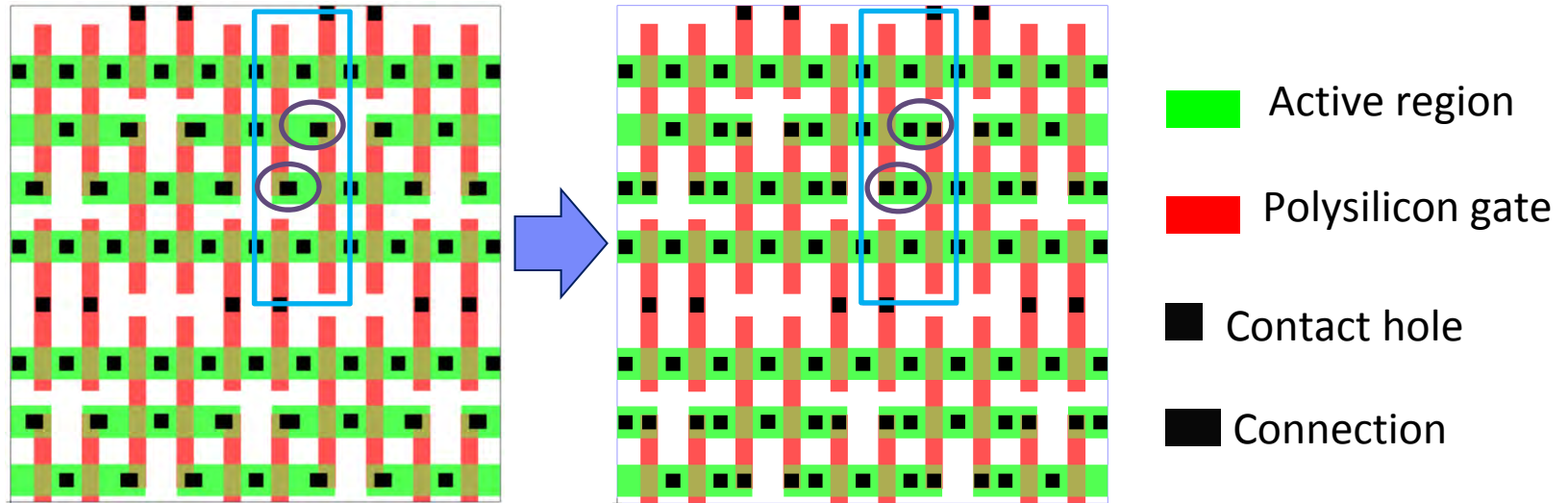
# IBM 22-nm SRAM Contact Holes Layout



\*Double pattern and double etch process were used to achieve these 26 nm size contact holes.

*Haran, B. S. Proc. IEDM (2008).*

# DSA-Aware Contact Holes for SRAM



## Template mask layout

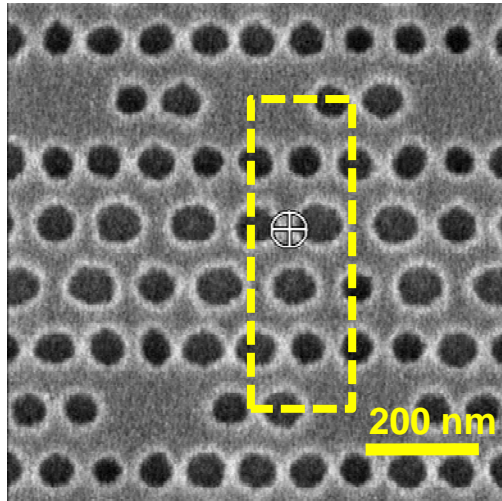
**Size:** 56nm (contacts)  
 56 x 70 nm (connection)

**Pitch:** x-axis=90nm  
 y-axis=110nm

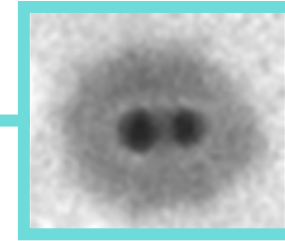
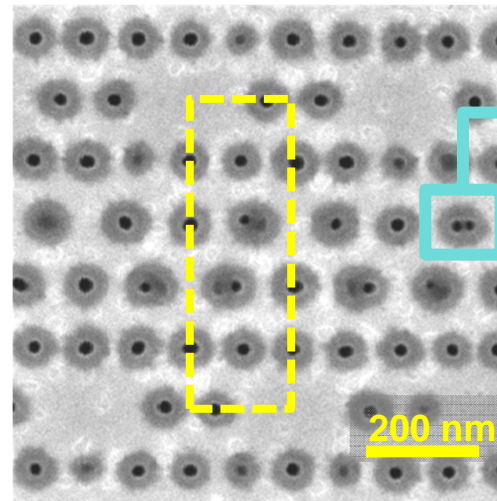


# DSA Patterned Contact Holes for SRAM

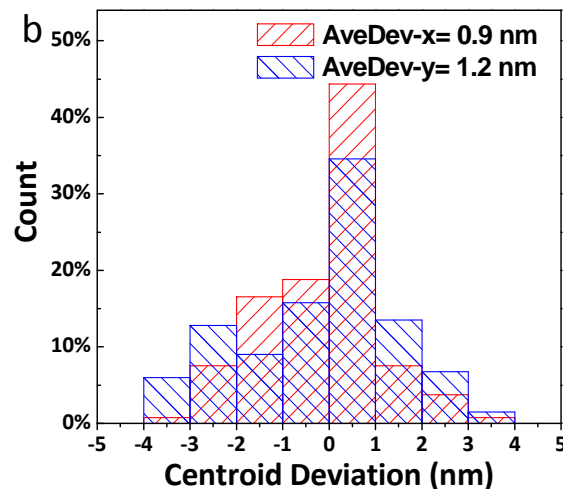
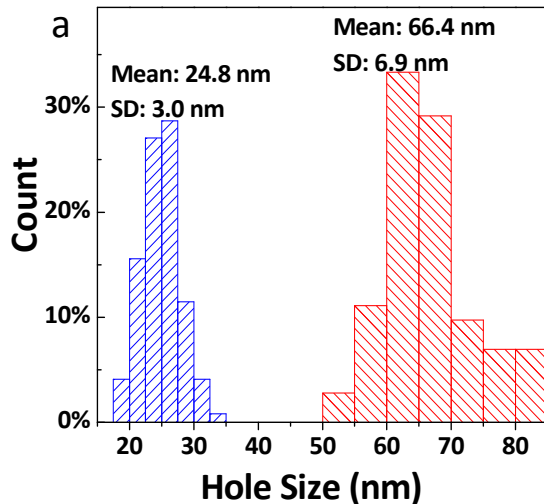
Template SEM



DSA SEM



- 300mm wafer
- 193 nm immersion Litho
- Industrial compatible sol.



Template  $\sim 66.4 \pm 7 \text{ nm}$

Contact hole  $\sim 25 \pm 3 \text{ nm}$

Centroid  $\Delta x \sim 0.9 \text{ nm}$

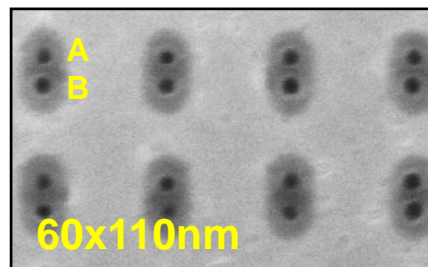
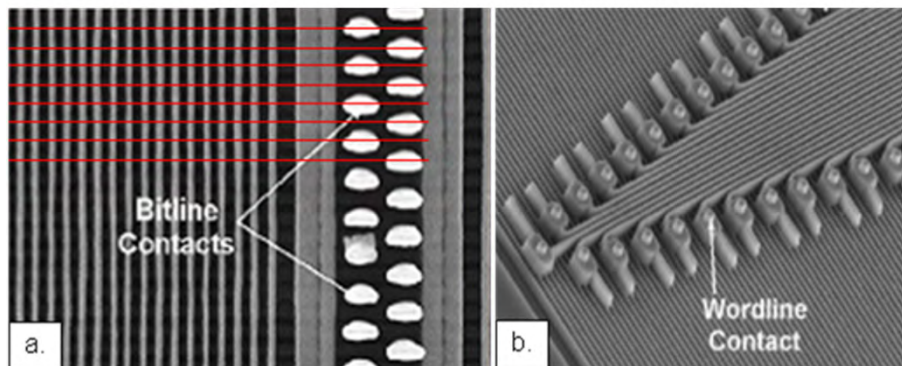
Centroid  $\Delta y \sim 1.2 \text{ nm}$

X.-Y. Bao, H. Yi ... H.-S. P. Wong, *IEDM*, p. 167, 2011



# Contact Holes for NAND (strategy)

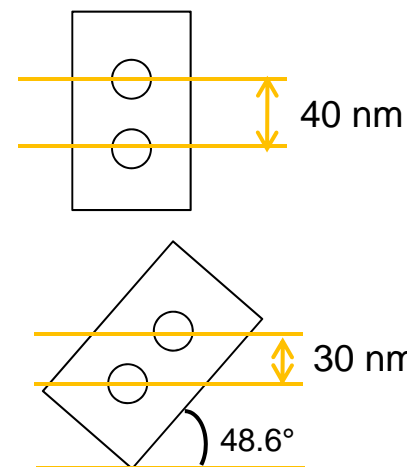
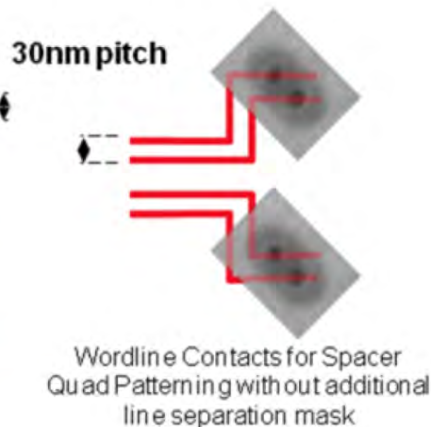
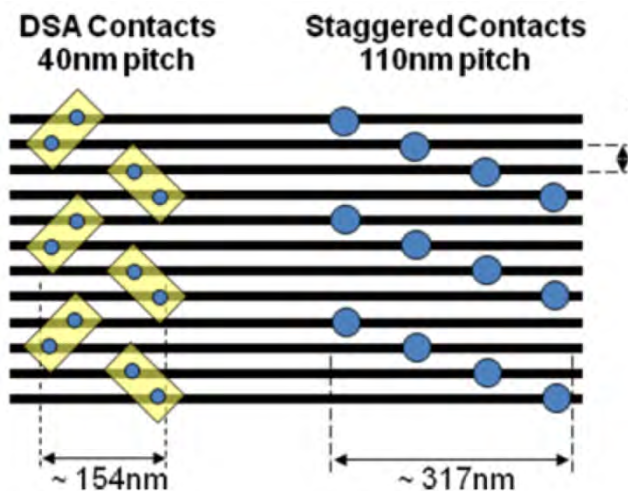
## 2-hole templates for NAND



15 nm hole size  
40 nm pitch

(source: UBM Techinsights)

Rotate to fit 30nm pitch



Extend to 15-nm NAND

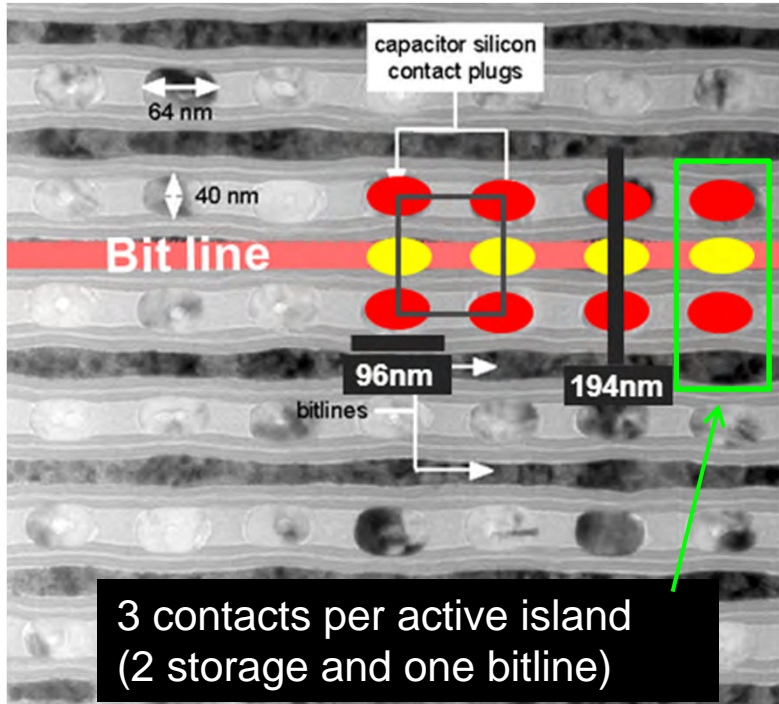
X.-Y. Bao, H. Yi ... H.-S. P. Wong, *IEDM*, p. 167, 2011



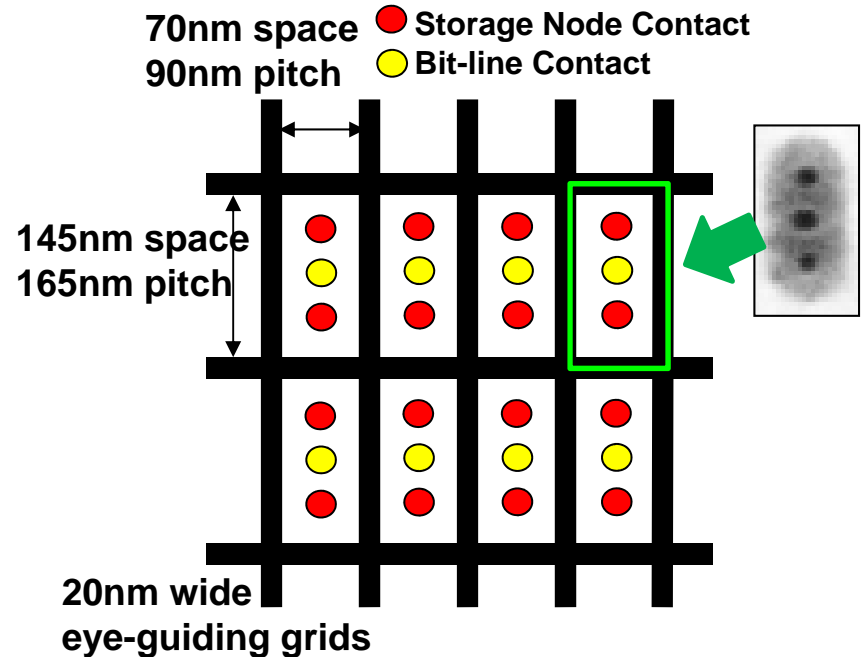


# Contact holes for DRAM (strategy)

## 3-hole templates for DRAM

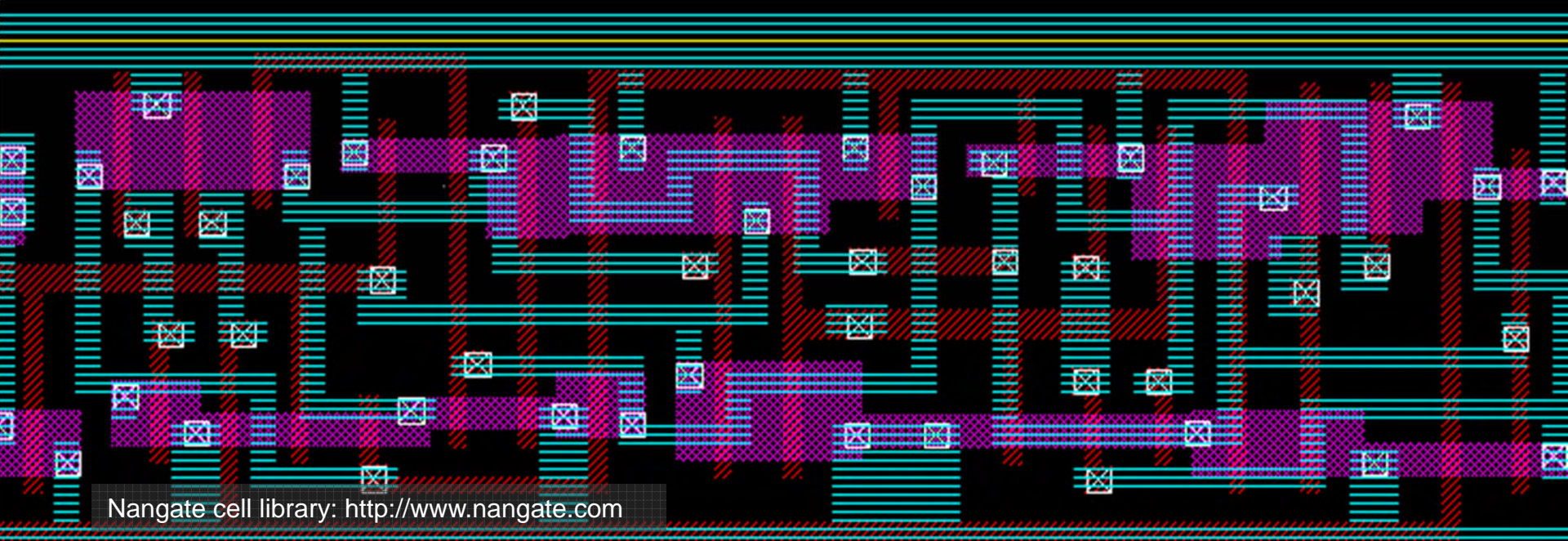


Example of 3x-nm DRAM  
(Source: Chipworks)

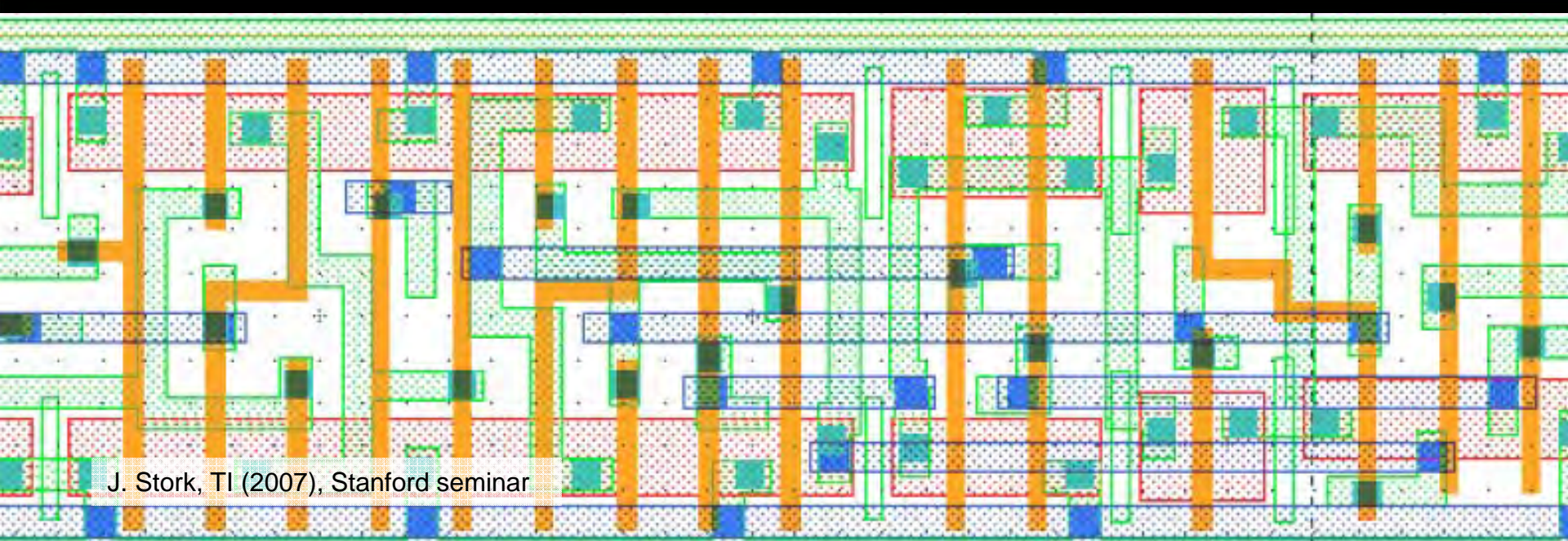


Shrink to 2x-nm DRAM  
3-hole templates (70x145nm)





Nangate cell library: <http://www.nangate.com>

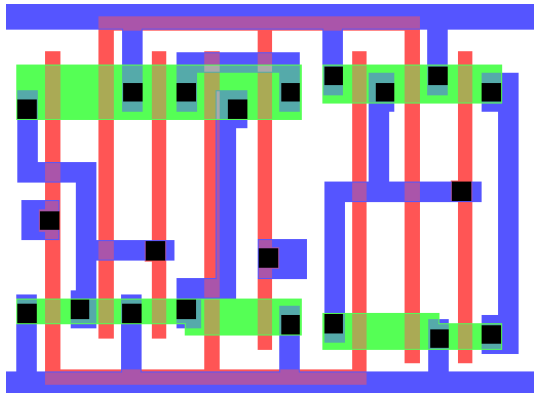


J. Stork, TI (2007), Stanford seminar



# Contacts for Random Logic Circuit

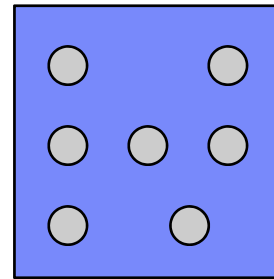
Example: Conventional  
45nm HA-X1 Layout



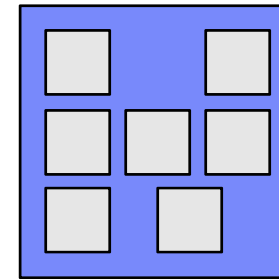
Source: Nangate 45nm Open Cell Library

## Challenges for DSA patterning

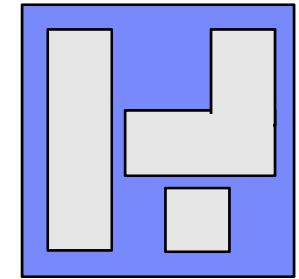
- Overcome resolution limits
- Irregular contact distribution
- Guiding template design
- Optimal template size and shape



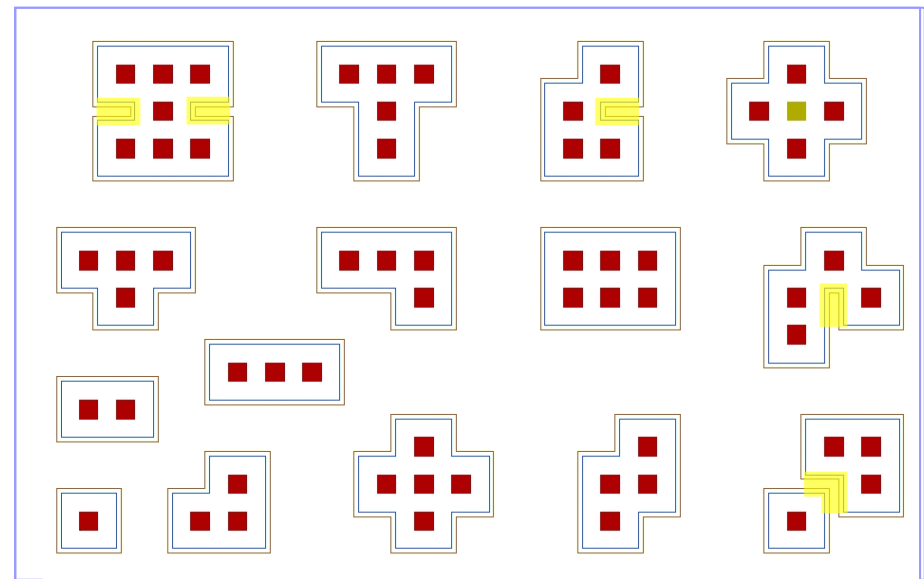
Contact hole  
layout



Design 1



Design 2



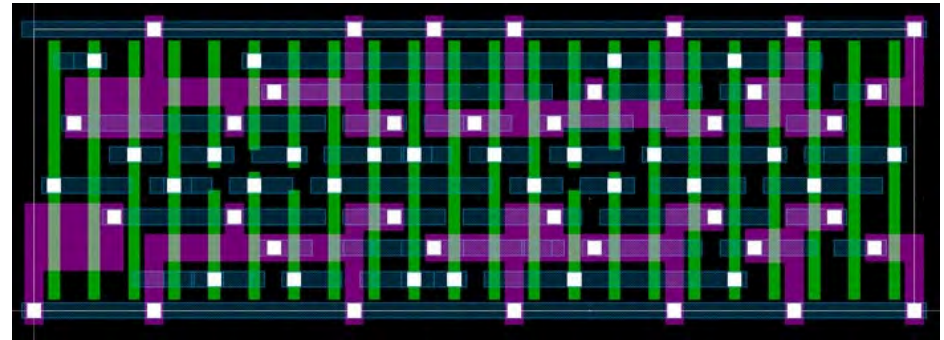
Courtesy of Jason Sweis, Cadence Design Systems

# DSA-Aware Layout: Simplifying Template Design

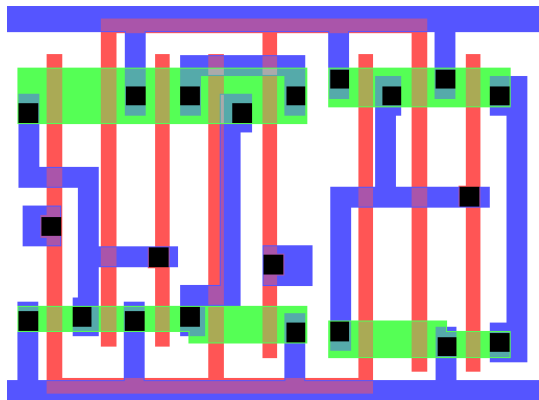
## Starting Point: Gridded Design Rule (GDR)

- Lines: parallel, single width & pitch
- Contacts: positioned only at pre-determined grid points

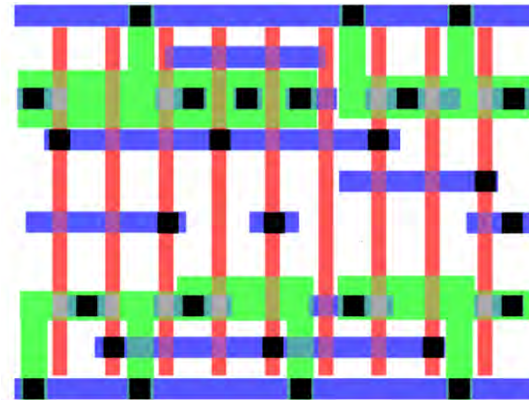
## Scan-D Flip Flop designed with Gridded Design Rules



Source: <http://www.tela-inc.com>



Conventional HA-X1 Layout



DSA-Aware HA-X1 Layout

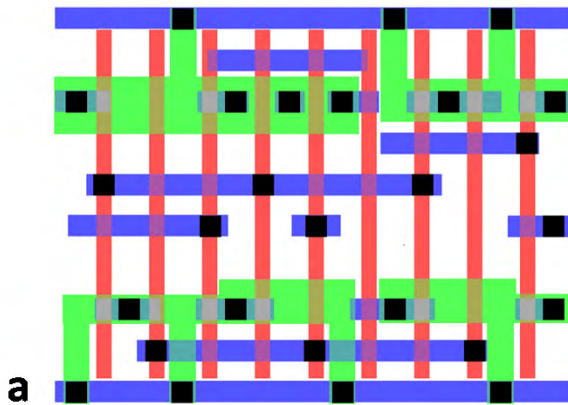
■ Metal 1   
 ■ Poly   
 ■ Active Region   
 ■ Contact

M2 vertical direction routing not shown for the sake of clarity

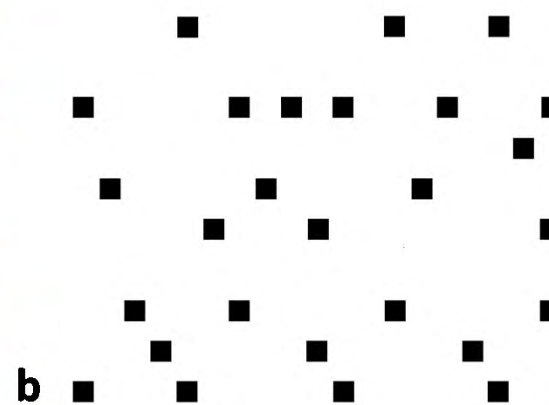
- Transistor sizes and connections (pin-out) unchanged
- No area penalty

# Random Logic Circuit Patterning: 1-bit Half Adder

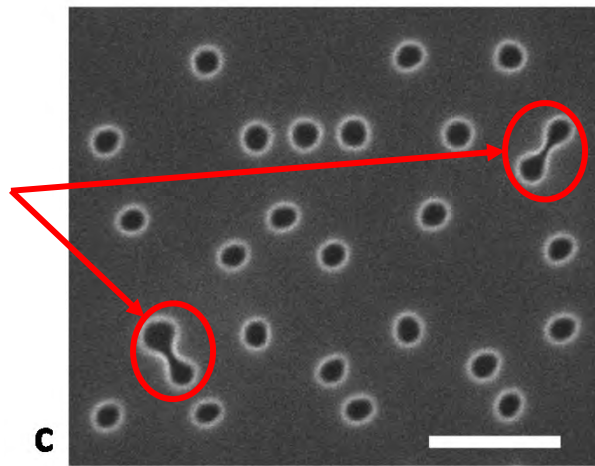
DSA-aware HA-X1



Contact Hole Layout

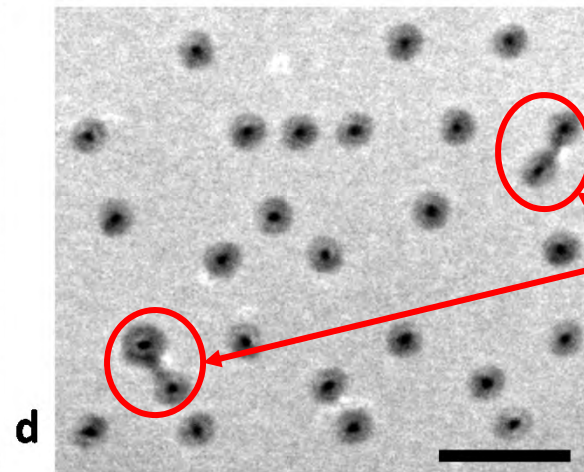


Template defects



Template (SEM)

DSA heal defects

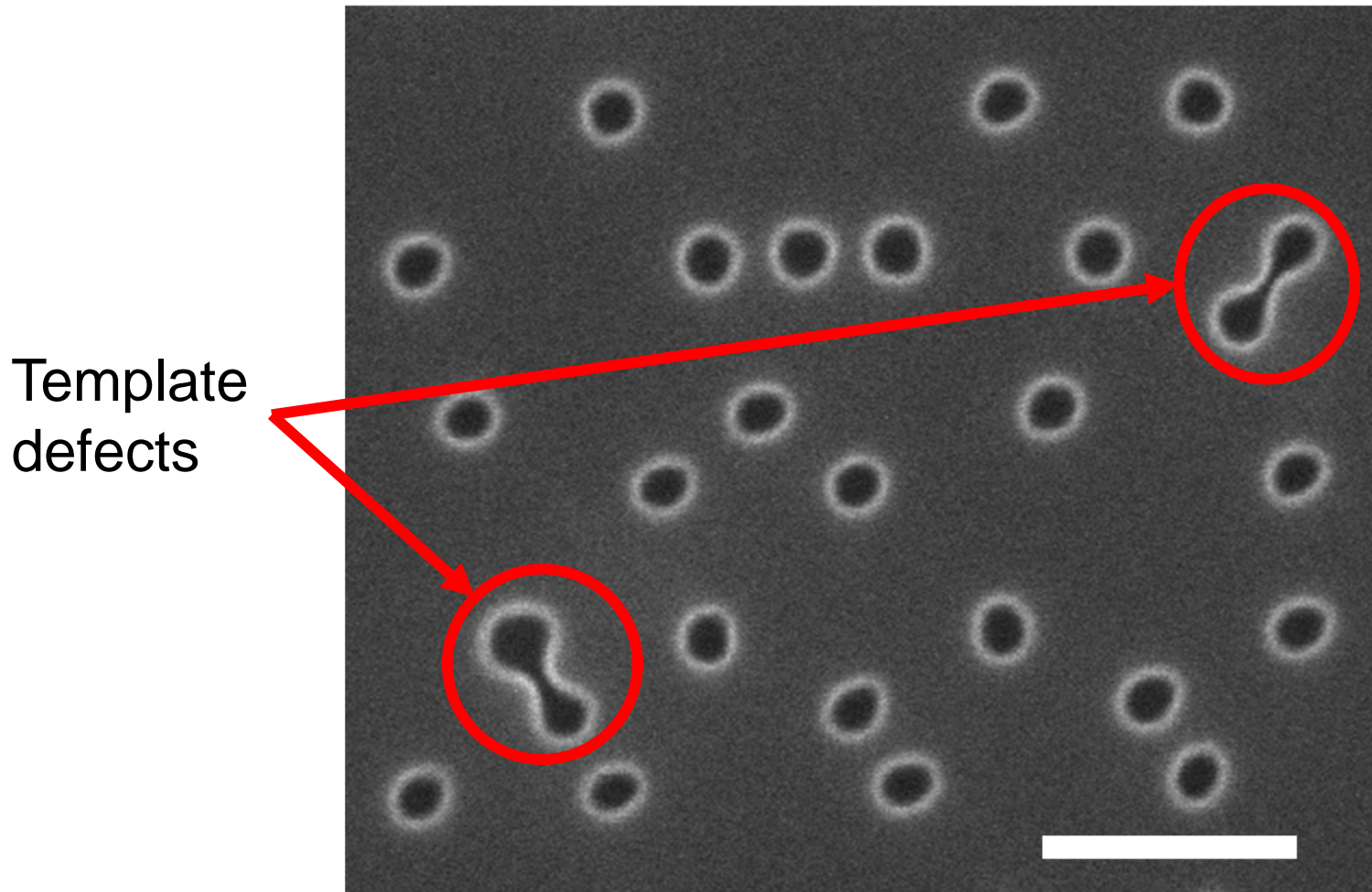


DSA results (SEM)

Scale bar: 200nm



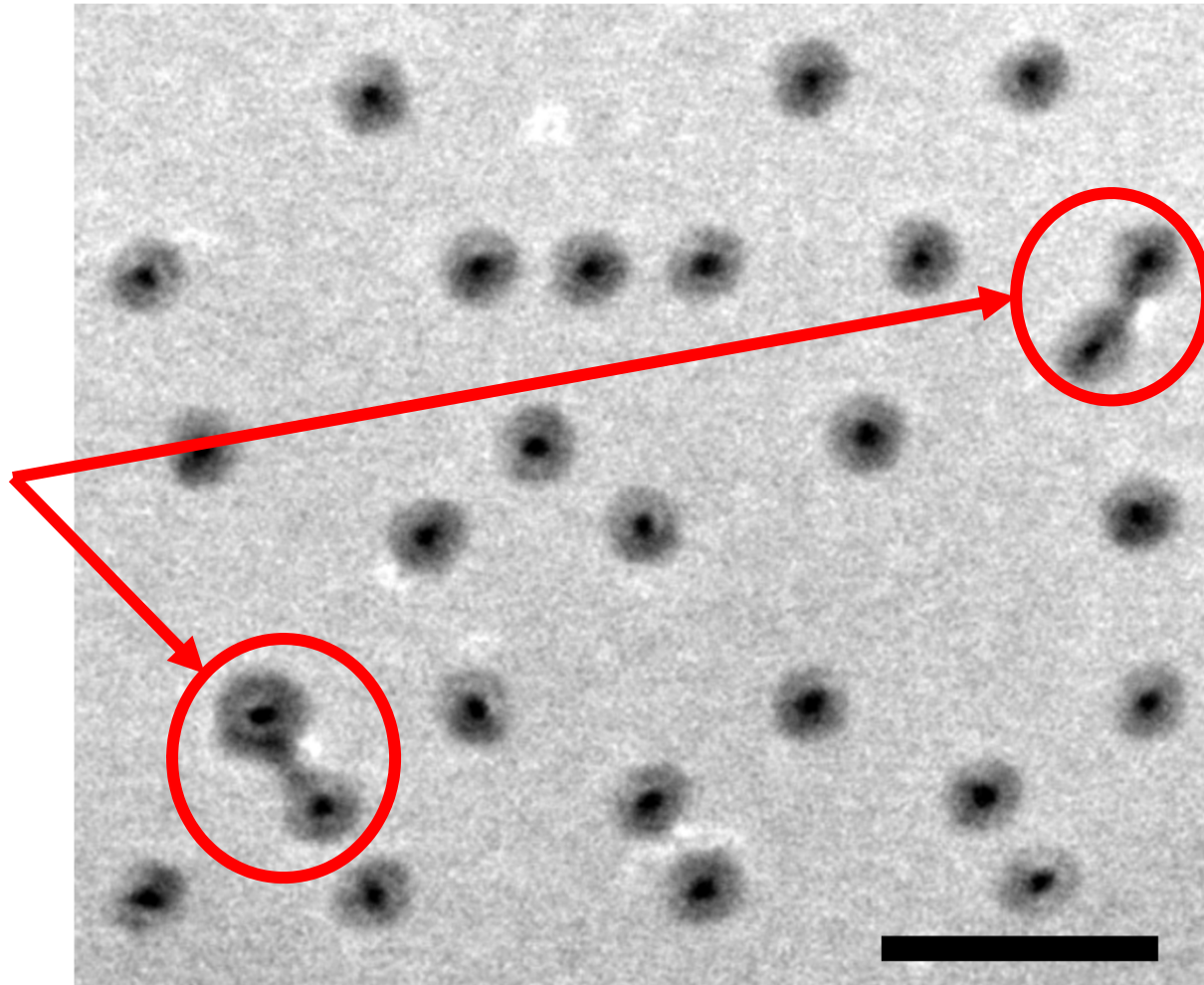
# Random Logic Circuit Patterning: 1-bit Half Adder



Scale bar: 200nm

# Random Logic Circuit Patterning: 1-bit Half Adder

DSA  
heals  
defects

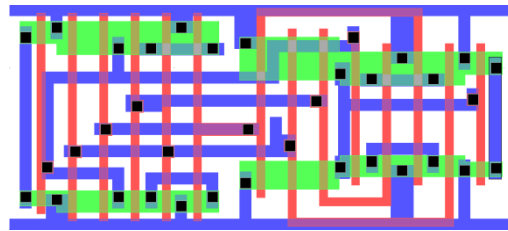


Scale bar: 200nm



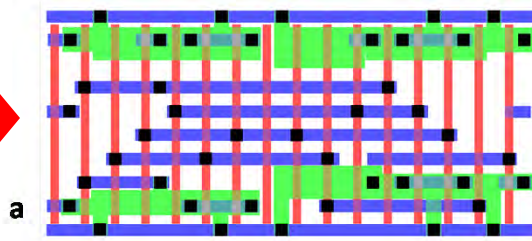
# Random Logic Circuit Patterning: 1-bit Full Adder

Conventional FA-X1  
(Nangate 45nm Open Cell Library)

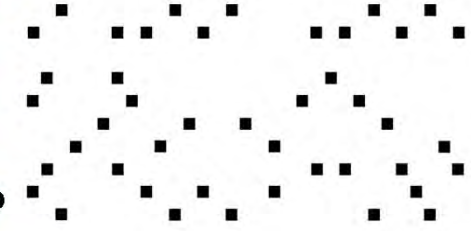


■ Metal 1 ■ Poly ■ Active Region ■ Contact

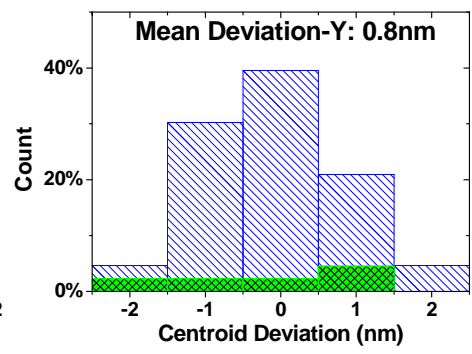
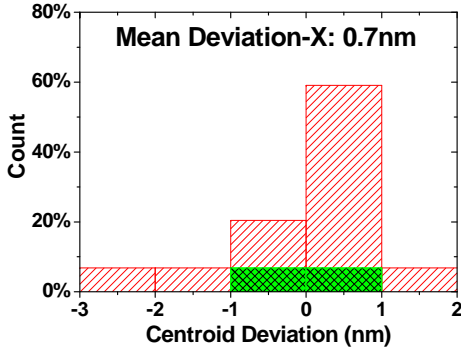
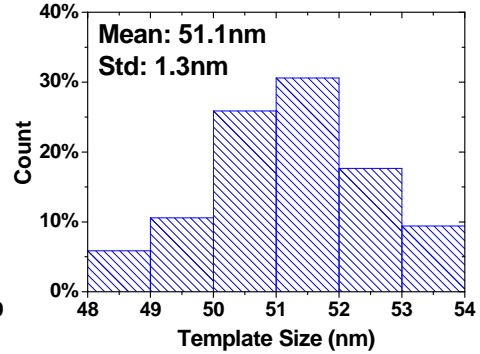
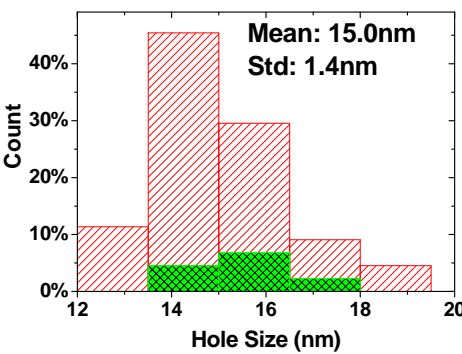
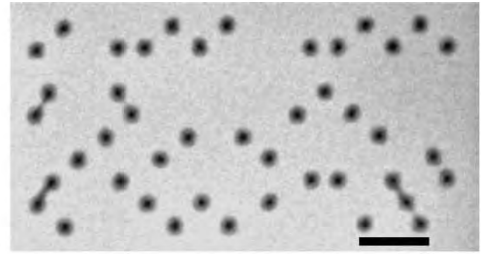
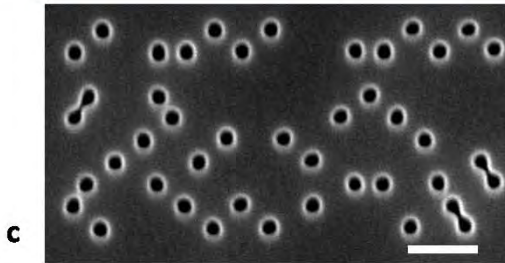
DSA-aware FA-X1



Contact Hole Layout



**Merged templates don't affect  
DSA holes overlay accuracy  
and size variation strongly**



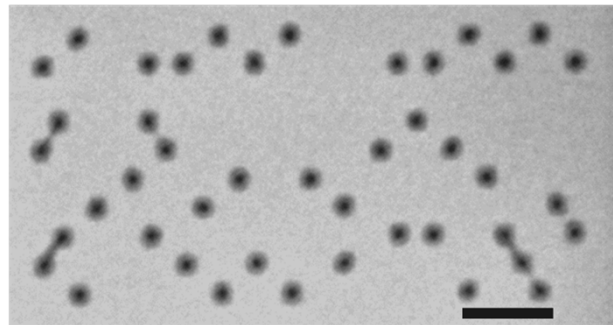
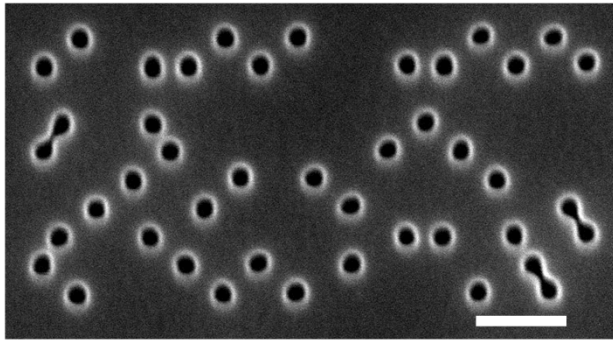
**Green histogram:** represent holes in merged templates.





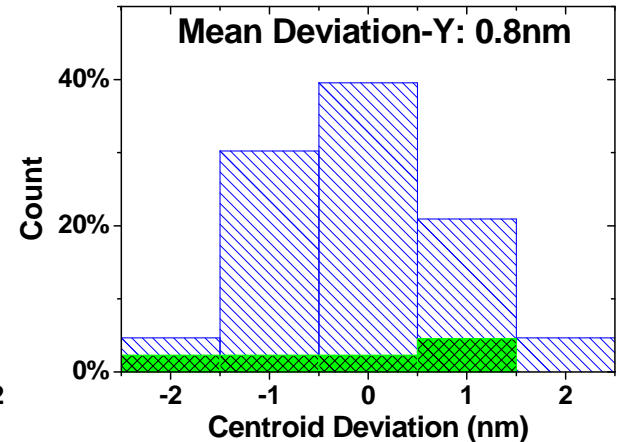
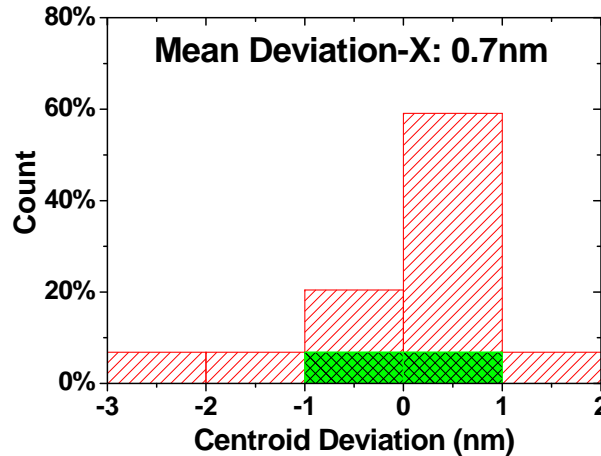
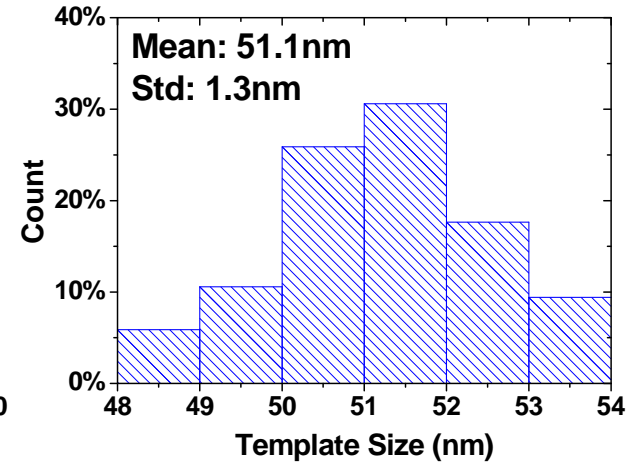
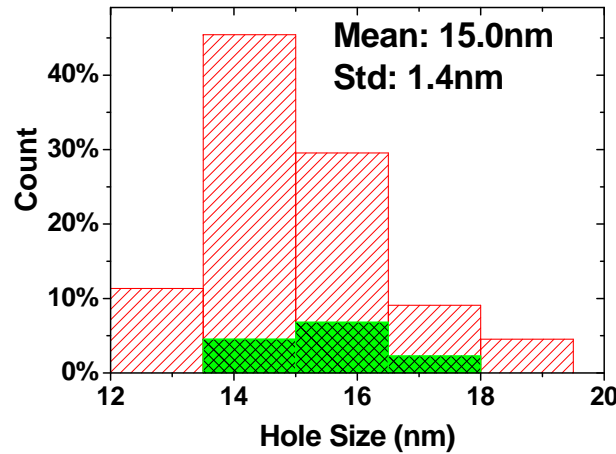
# Random Logic Circuit Patterning: 1-bit Full Adder

Merged templates don't affect DSA holes overlay accuracy and size variation



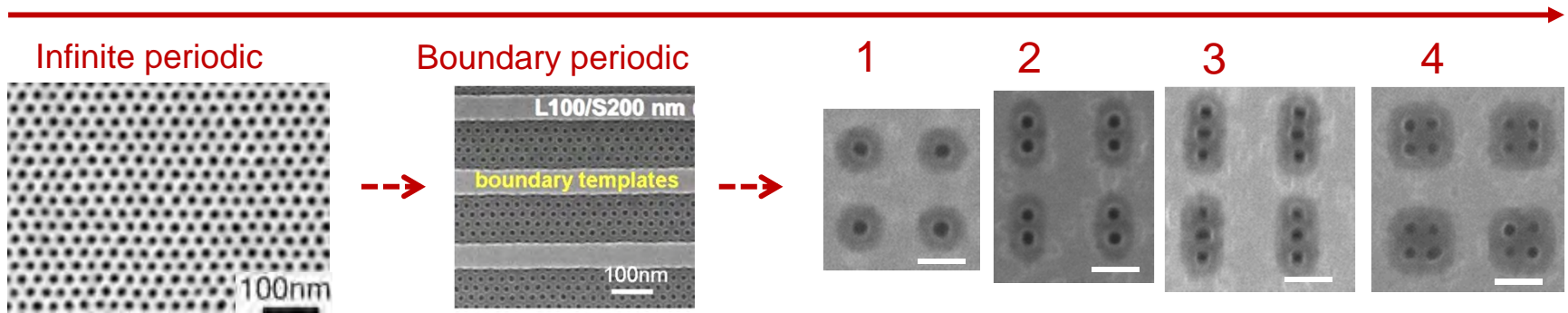
Scale bar: 200nm

**Green histogram:** represent holes in merged templates



# DSA for Contact Hole Patterning

## DSA Evolution



**193 nm immersion + DSA**

**=**

**Extension of double-patterning**



# Looking Forward

- **Defectivity**
  - 300 mm wafer, statistical data
- **EDA tool**
  - Think OPC, DFM
  - Application of DSA must be transparent to designers
- **Develop DSA-aware template design rules**
  - Experiments, modeling

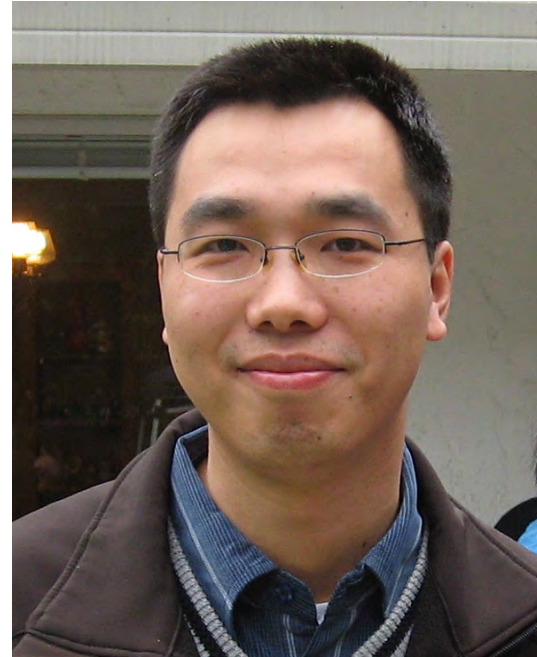




## Graduated Student and Post-Doc



**Li-Wen Chang**  
PhD 2010  
Currently with Xilinx



**Xinyu Bao**  
Post-doc (2008 – 2010)  
Currently with AMAT



# Collaborators

- **Applied Materials (Chris Bencher and team)**
- **Prof. Subhasish Mitra (Stanford, EE & CS Dept.)**



# Sponsors and Collaborators

